

Title (en)  
MOISTURE-CURABLE HOT MELT ADHESIVE

Title (de)  
FEUCHTIGKEITSHÄRTBARER HEISSSCHMELZKLEBER

Title (fr)  
ADHÉSIF THERMOFUSIBLE DURCISSABLE SOUS L'ACTION DE L'HUMIDITÉ

Publication  
**EP 2528981 A2 20121205 (EN)**

Application  
**EP 10835037 A 20101201**

Priority  
• JP 2009273378 A 20091201  
• US 2010058522 W 20101201

Abstract (en)  
[origin: WO2011068847A2] The present invention provides a method for producing a moisture-curable hot melt adhesive. This moisture-curable hot melt adhesive is environmentally friendly, is compatible with the components therein, has high initial adhesion strength, has long open time and has high heat resistance after moisture curing. The moisture-curable hot melt adhesive comprises a (A) urethane prepolymer having an isocyanate group at the terminus, comprising, a (A) urethane-modified rosin, and a (B) copolymer of ethylene and a (meth)acrylic acid derivative, wherein the urethane prepolymer is obtained by the reaction of polyol with an isocyanate compound.

IPC 8 full level  
**C09J 175/04** (2006.01); **C08G 18/10** (2006.01); **C08G 18/36** (2006.01); **C08G 18/42** (2006.01); **C08L 75/06** (2006.01); **C08L 93/04** (2006.01); **C09J 133/04** (2006.01); **C09J 133/08** (2006.01); **C09J 133/12** (2006.01); **C09J 175/06** (2006.01); **C09J 193/04** (2006.01)

CPC (source: EP)  
**C08G 18/10** (2013.01); **C08G 18/36** (2013.01); **C08G 18/4288** (2013.01); **C08L 33/08** (2013.01); **C08L 33/12** (2013.01); **C08L 67/02** (2013.01); **C09J 133/08** (2013.01); **C09J 133/12** (2013.01); **C09J 175/04** (2013.01); **C09J 175/06** (2013.01); **C09J 193/04** (2013.01); **C08G 2170/20** (2013.01); **C08L 75/06** (2013.01); **C08L 93/04** (2013.01); **C08L 2205/03** (2013.01)

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
**WO 2011068847 A2 20110609**; **WO 2011068847 A3 20111117**; BR 112012013368 A2 20170404; EP 2528981 A2 20121205; EP 2528981 A4 20140618; JP 2011116817 A 20110616

DOCDB simple family (application)  
**US 2010058522 W 20101201**; BR 112012013368 A 20101201; EP 10835037 A 20101201; JP 2009273378 A 20091201